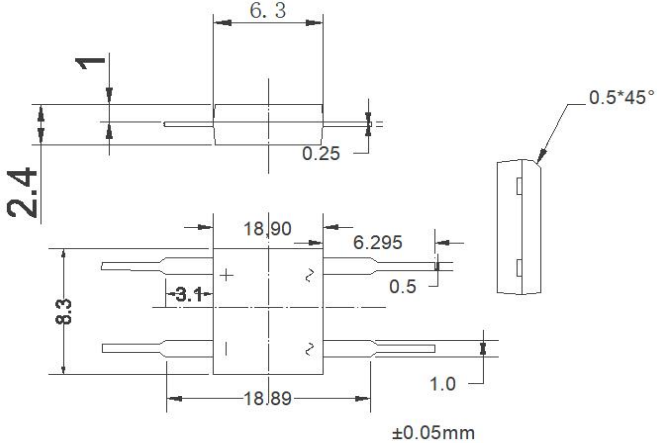


特征/Features <ul style="list-style-type: none"> ◆ GPP芯片 Glass passivated chip ◆ 低反向漏电流 Low Reverse Leakage Current ◆ 高耐浪涌电流能力 High surge current capability ◆ 接线端与壳体间绝缘耐压2500V Case to Terminal Isolation Voltage 2500V 	外形尺寸/Outline Dimensions Case: DB Series Dimensions in millimeters 
机械参数/Mechanical Data <ul style="list-style-type: none"> ◆ 本体: 塑封 Case: plastic package ◆ 标识/极性: 本体标记 Marking / Polarity: Marked on Body ◆ 重量: 约克 Weight: About 0.35 grams 	

极限值/Maximum Ratings and Thermal Characteristics @ Ta = 25°C unless otherwise noted

符号 Symbol	特性 Characteristic	DB2							单位 Unit
		005	01	02	04	05	06	07	
V _{RRM}	最大反向重复峰值电压 Maximum Recurrent Peak Reverse Voltage	50	100	200	400	600	800	1000	V
I _{F(AV)}	平均整流输出电流 Average Forward Output Rectified Current@Ta =120°C	2							A
V _F	正向峰值电压 Forward Voltage Per Leg @I _{FM} =2.0A	1.02							V
I _{FSM}	正向浪涌电流 Peak Forward Surge Current 8.3ms Single Half Sine-wave superimposed on rated load	60							A
I _R	反向漏电流 Maximum DC reverse current at rated DC blocking voltage per leg	5 500							uA
i ² t	热容值 Rating for fusing (t<8.3ms)	15							A ² S
V _{isol}	绝缘耐压 Rms isolation voltage from case to leads	2500							V
C _J	典型结电容 Typical Junction Capacitance	18							pF
R _{θJC}	热阻 Maximum thermal resistance per leg	10							°C/W
T _j , T _{STG}	结温, 存储条件 Operating Junction and storage temperature range	-55~150							°C

Note:
 (1) Junction to case with heatsink
 (2) Recommended mounting position is to bolt down on heatsink with silicone thermal compound for maximum heat transfer with M3 screw .

◆ 特性曲线 (典型) Characteristics(Typical)

Fig 1-forwardCurrent derating Curve
图1正向电流降额曲线

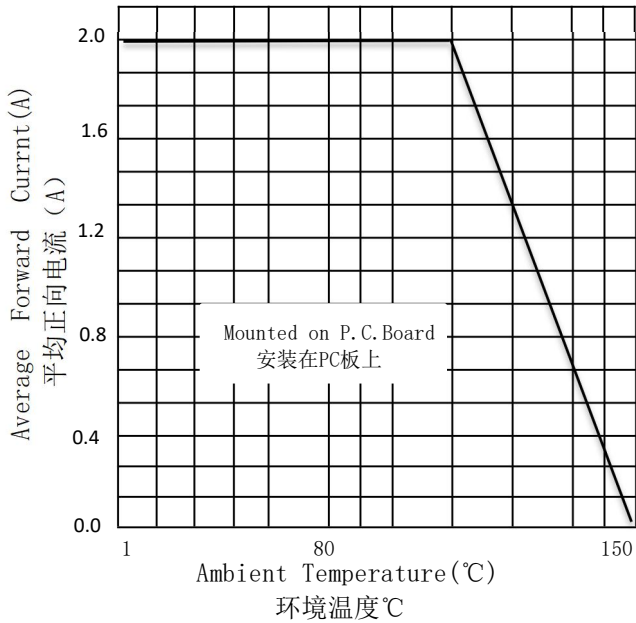


Fig.2-Maximum Non-Repetitive Surge Current
图2 最大不重复正向浪涌曲线

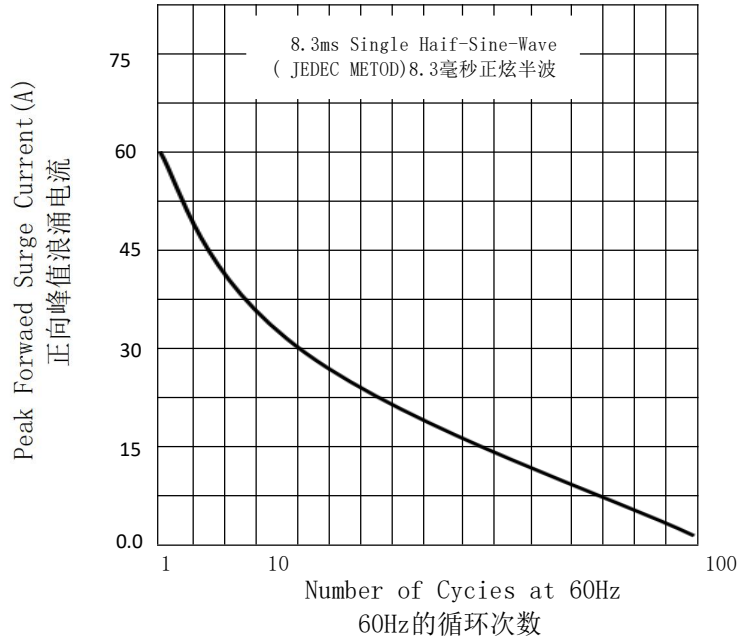


Fig.3-Typical Reverse Characteristics
图3. 典型的反向特性

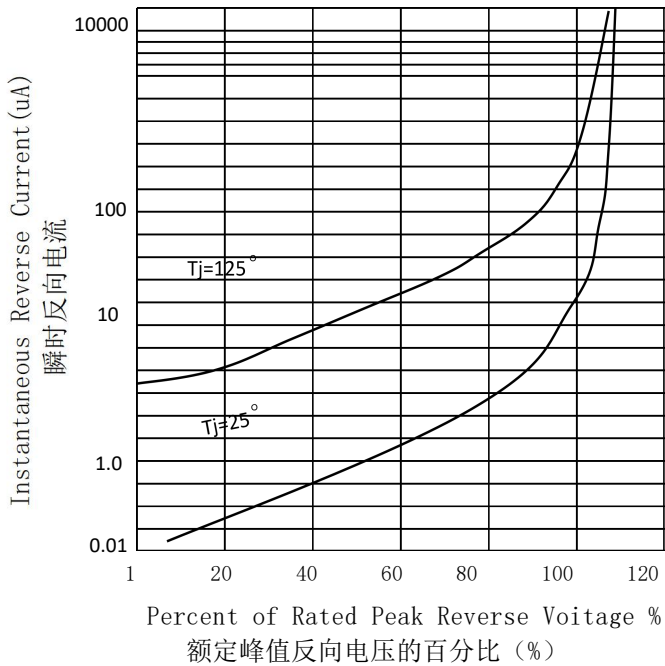


Fig.4-Typical Forward Characteristics
图4. 典型的正向特性

